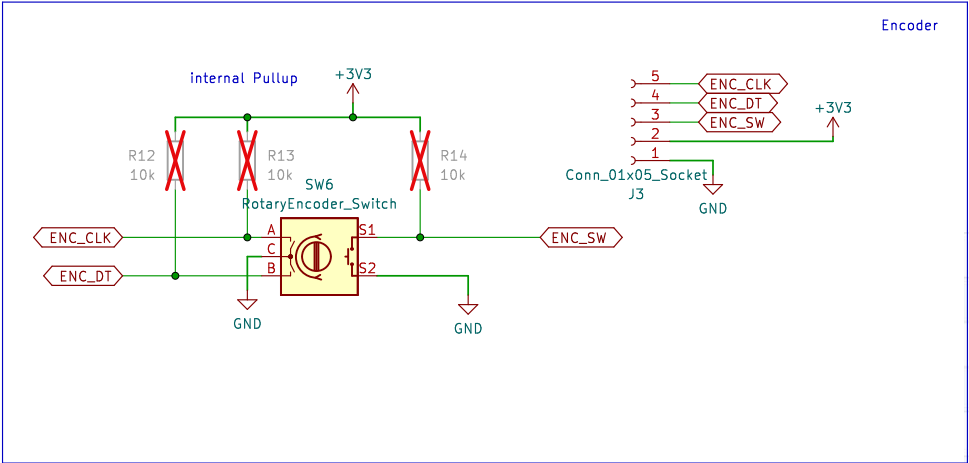
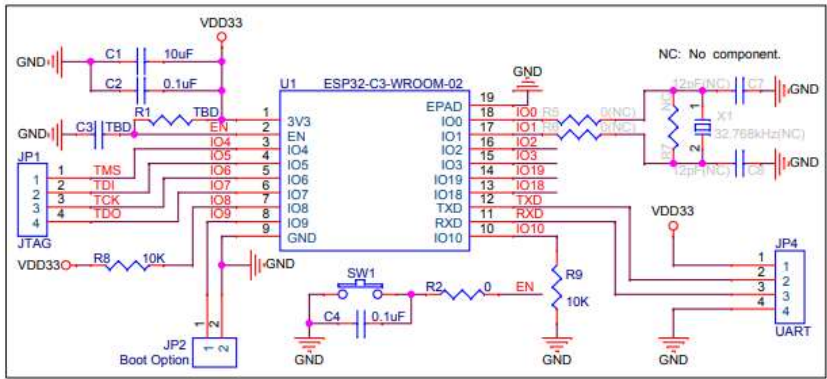
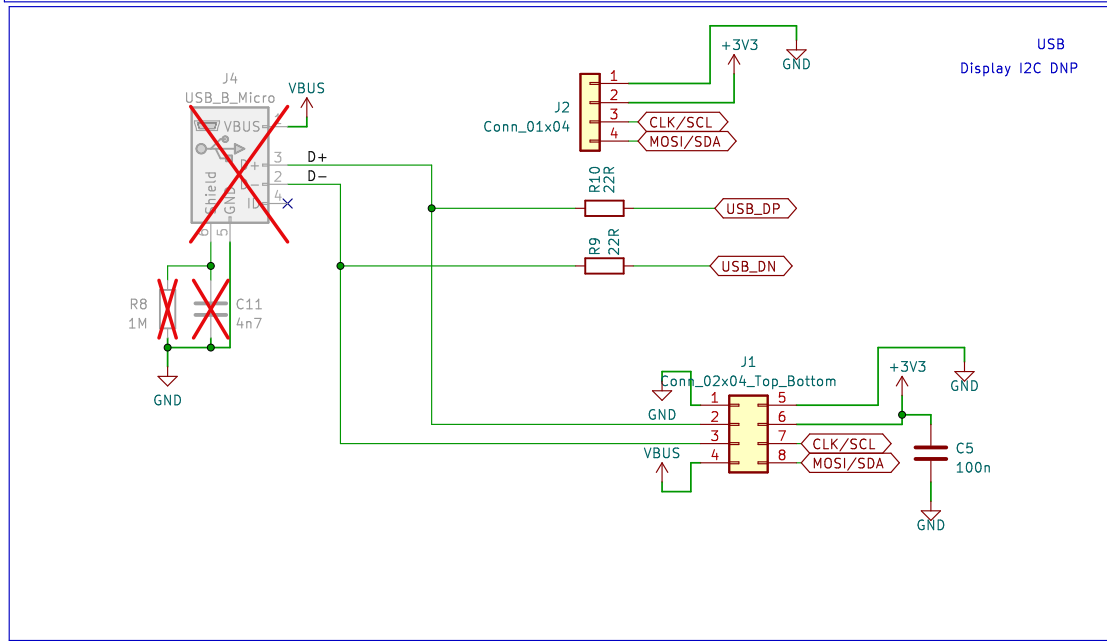


Standard SPI Protocol		Extended SPI Protocol
Full-Duplex SPI Signal	Half-Duplex SPI Signal	FSPI Bus Signal
MOSI	MOSI	FSPI <sub>D</sub> 7
MISO (MISO)	—	FSPI <sub>Q</sub> 2
CS	CS	FSPIC <sub>S0</sub> ~ 5 10
CLK	CLK	FSPICLK 6
—	—	FSPPWP
—	—	FSPIHD



Name	Type <sup>1</sup>	Function
G	G	Ground
3V3	P	3.3 V power supply
3V3	P	3.3 V power supply
RST	I	CHIP_PU
G	G	Ground
4	I/O/T	GPIO4, ADC1_CH4, FSPIHD, MTMS
5	I/O/T	GPIO5, ADC2_CH0, FSPIWP, MTDI
6 CLK	I/O/T	GPIO6, FSPICLK, MTCK
7 MOSI	I/O/T	GPIO7, FSPID, MTDO
G	G	Ground
8	I/O/T	GPIO8 <sup>2</sup> , RGB LED
9	I/O/T	GPIO9 <sup>2</sup>
5V	P	5 V power supply
5V	P	5 V power supply
G	G	Ground

Name	Type <sup>1</sup>	Function
G	G	Ground
0	I/O/T	GPIO0, ADC1_CH0, XTAL_32K_P
1	I/O/T	GPIO1, ADC1_CH1, XTAL_32K_N
2 MISO	I/O/T	GPIO2 <sup>2</sup> , ADC1_CH2, FSPIQ
3	I/O/T	GPIO3, ADC1_CH3
G	G	Ground
10 CS	I/O/T	GPIO10, FSPICS0
G	G	Ground
RX	I/O/T	GPIO20, U0RXD
TX	I/O/T	GPIO21, U0TXD
G	G	Ground
18	I/O/T	GPIO18
19	I/O/T	GPIO19
G	G	Ground
G	G	Ground



#### Figure 4: Peripheral Schematics

- Soldering the EPAD to the ground of the base board is not a must, though doing so can get optimized thermal performance. If you do want to solder it, please ensure that you apply the correct amount of soldering paste.
- To ensure the power supply to the ESP32-C3 family chip is stable during power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually  $R = 10\text{ k}\Omega$  and  $C = 1\text{ }\mu\text{F}$ . However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset sequence timing of the chip. For power-up and reset sequence timing diagram of the ESP32-C3 family chip, please refer to Section Power Scheme in [ESP32-C3 Family Datasheet](#).

